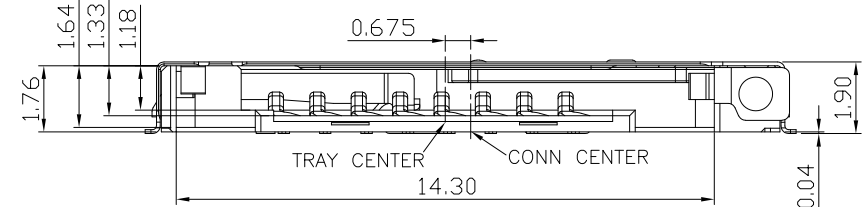
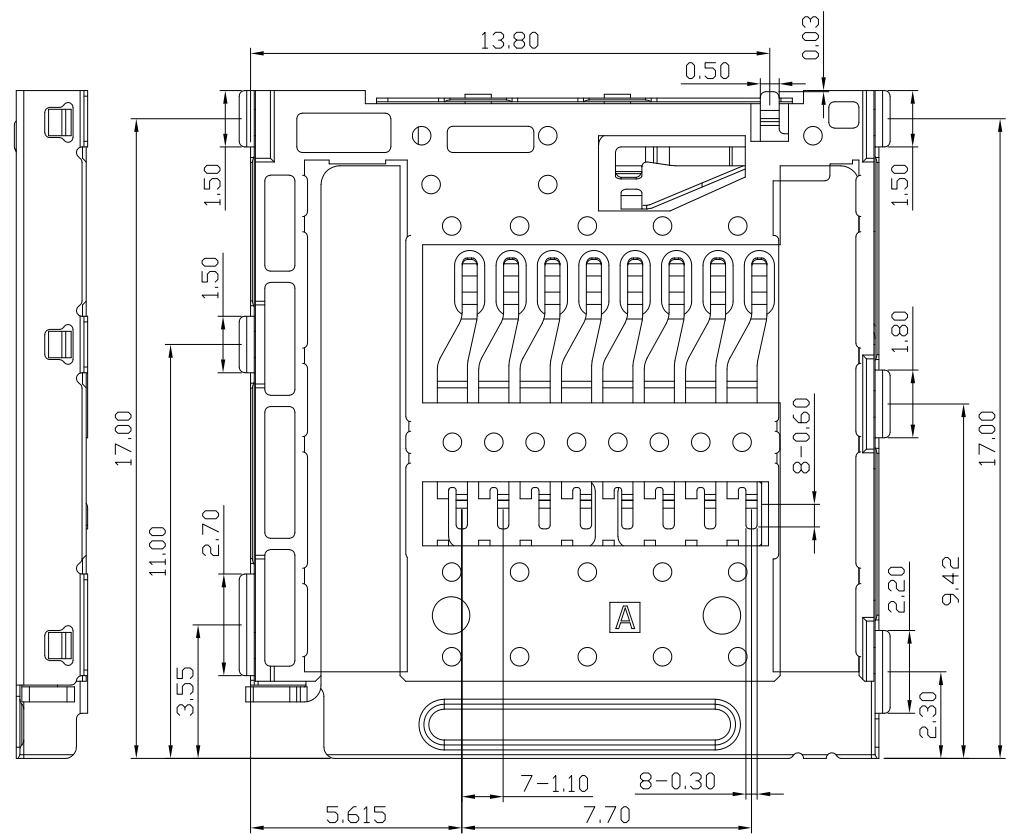
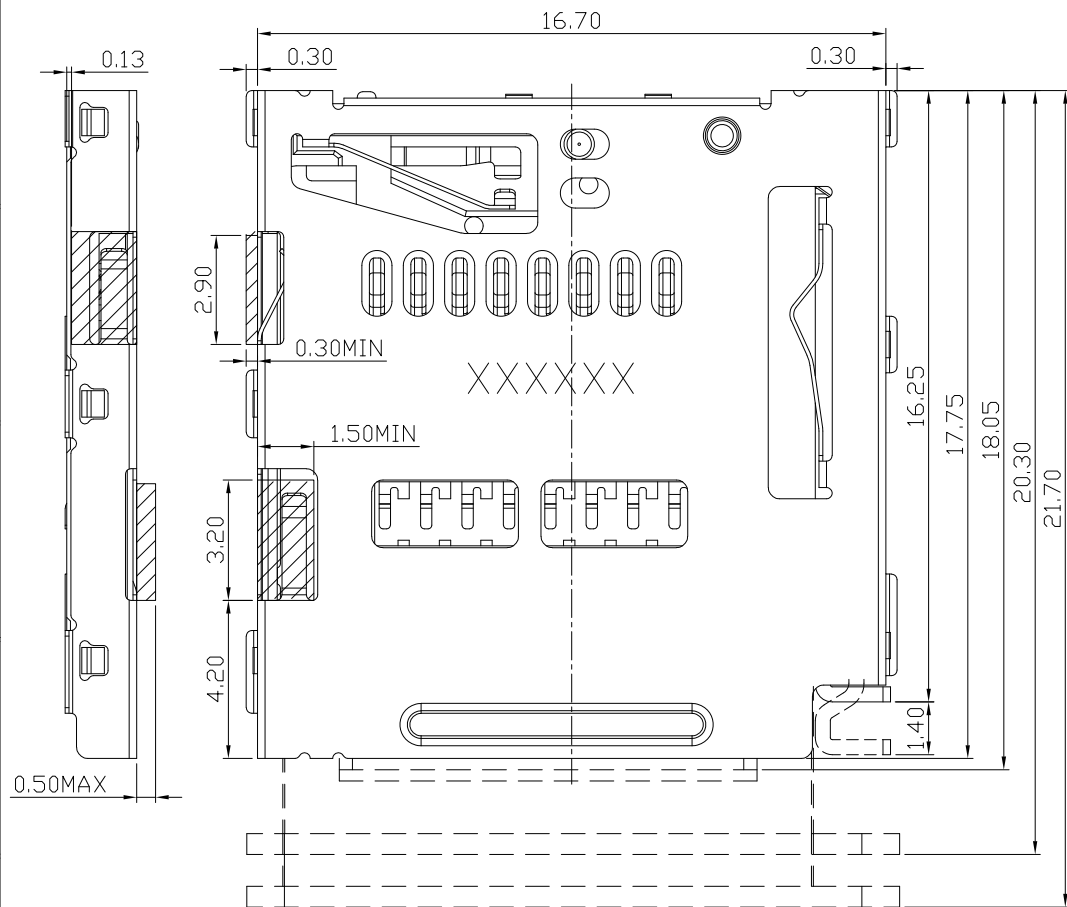
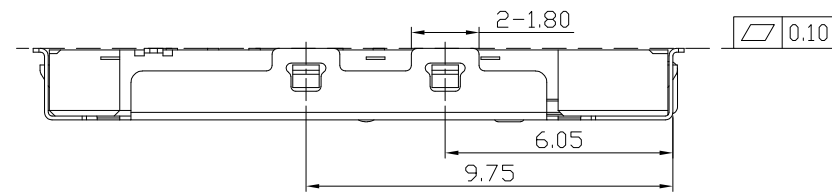


REV.	ECN.NO.	MODIFY.CONTENT
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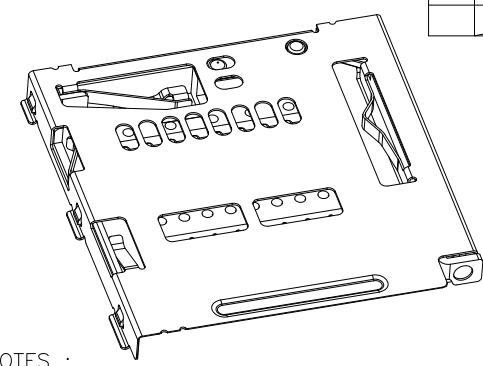
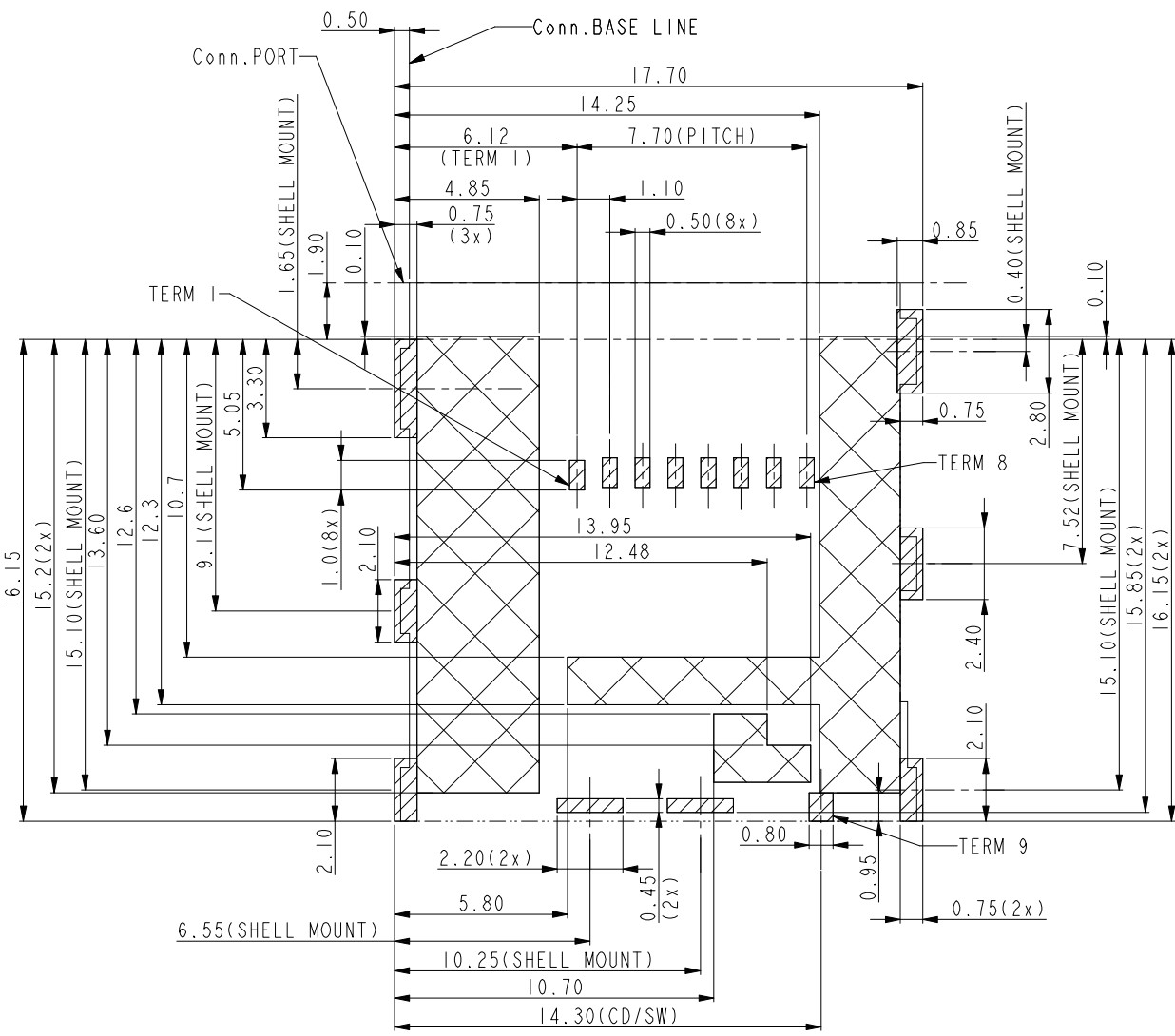


RoHS Compliant **HF**

GENERAL	TOLERANCE	DWG.NO.	MR252-AP401-00	PART.NO.	MR252-AP401-**	DRAWN	L.M.J 2021.04.12
x.±0.50	x.°± 5°	REV.	X1	TITLE	Micro SD With Tray H1.90	CHECKED	
.x±0.25	.x°± 2°	SIZE		SHEET	1 OF 3	APPROVED	
.xx±0.15	.xx°± 1°	A4					

UNIT	mm	SCALE	1:1
东莞市欧联电子科技有限公司 DONGGUAN OLN ELECTRONICS TECHNOLOGY CO., LTD.			

REV.	ECN.NO.	MODIFY.CONTENT
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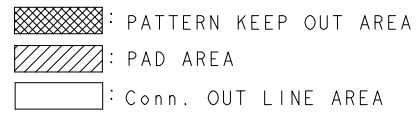


- NOTES :
- MATERIAL :
 - HOUSING:LCP S475 UL94 V-0, BLACK COLOR.
 - SHELL: STAINLESS STEEL SUS304.
 - CONTACT: COPPER ALLOY C5210.
 - FINISH :
 - CONTACT: GOLD PLATING ON CONTACT AREA, 1u" GOLD MIN ON SOLDERTAIL AREA. 50u" MIN NICKEL PLATING OVERALL.
 - SHELL: 30u" MIN SOLDERABILITY NICKEL PLATING OVERALL.
 - ELECTRICAL CHARACTERISTICS:
 - OPERATING VOLTAGE : 100V AC(rms)/DC.
 - CURRENT RATING : 0.5 A.
 - OPERATING TEMPERATURE: -25°C~+85°C.
 - CONTACT RESISTANCE: 100 m OHMS MAX.
 - INSULATION RESISTANCE: 100OM OHMS MIN. AT 250VDC.
 - DIELECTRIC WITHSTANDING VOLTAGE:500 VAC/1MINUTE.

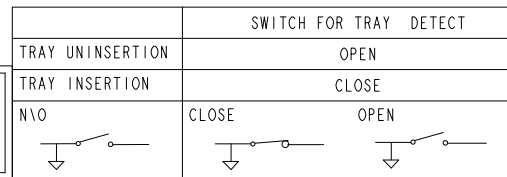
PART.NO.:
MR252-AP401-**

- 08: 功能区镀金1U", 锡脚Gold Flash
- 09: 功能区镀金3U", 锡脚Gold Flash
- 10: 功能区镀金5U", 锡脚Gold Flash
- 11: 功能区镀金15U", 锡脚Gold Flash
- 12: 功能区镀金30U", 锡脚Gold Flash

RECOMMENDED P.C.BOARD LAYOUT (MOUNT SURFACE)
TOLERANCE±0.05



OPENING /CLOSE OF SWITCH



TERM1	DAT2
TERM2	CD/DAT3
TERM3	CMD
TERM4	Vdd
TERM5	CLK
TERM6	Vss
TERM7	DAT0
TERM8	DAT1
TERM9	DETECT LEVER (CD PIN)



GENERAL TOLERANCE		DWG.NO.	MR252-AP401-00	PART.NO.	MR252-AP401-**	DRAWN	L.M.J 2021.04.12
x.±0.50	x.*± 5°	REV.	A	TITLE	Micro SD With Tray H1.90	CHECKED	
.x±0.25	.x.*± 2°	SIZE		SHEET	2 OF 3	APPROVED	
.xx±0.15	.xx.*± 1°	A4					

UNIT	mm	SCALE	1:1
东莞市欧联电子科技有限公司 DONGGUAN OLN ELECTRONICS TECHNOLOGY CO., LTD.			